

Industrial session schedule

Monday 3rd September

Hall 1, 18:00 - 20:00

Session Chairs: Richard McMahon, University of Warwick; Craig Fisher, UTC

Time	Institution or organisation	Name	Title
18:00	Wolfspeed, A Cree Company	Chris Dimino	Wolfspeed Materials Update
18:08	Dow Chemical Company	Jianwei Dong	Partnering for the Future with DuPont Electronics and Imaging on SiC Materials
18:16	Revasum	Rob Rhoades	Streamlined SiC Substrate Grind and CMP
18:24	AIXTRON SE	Dr Frank Wischmeyer	Accelerated adoption of SiC in power electronics applications
18:32	II-VI Advanced Materials	Dr Andy Souzis	SiC Market Demand, Manufacturing Expansion and Technology Status at II-VI Advanced Materials
18:40	Lasertec US	Eru Yamamura	SICA for High Volume Manufacturing Inspection Solutions
18:48	centrotherm international	Patrick Schmid	SiC Activation and Oxidation Technology Aspects
18:56	Oxford Instruments Plasma Technology (uk) Ltd	Dr Mark Dineen	How plasma process solutions help make the best SiC devices
19:04	LPE	Danilo Crippa	Automated Cassette-to-Cassette Silicon Carbide Epitaxial Reactor for 150mm and 200mm
19:12	Compound Semiconductor Applications Catapult	Alastair McGibbon	Supporting the Challenges of SiC System Integration
19:20	STMicroelectronics	Mario Saggio	
19:28	GT Advanced Technologies	Henry Chou	Enabling Volume Supply of Production Quality Silicon Carbide Crystal for Power Electronics
19:36	Silvaco Europe Ltd	Chris Marnoch	Simulation and Modelling SiC and Related Devices
19:44	CuttingEdge Ions, LLC	Brian Doherty	High temperature implants for SiC

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The International Convention Centre, Hall 1

As with previous ECSCRM/ICSCRM meetings, we will be hosting an industrial session allowing the top 15 industrial contributors to take to the stage and share their company's vision and latest developments in their field. This evening session will take place once the technical sessions are completed for the day. Drinks and light snacks will be provided.